

10-30-2002



Tab settings → → → ▼

To the Honorable Commissioner of Pat.

102266286

attached original documents or copy thereof.

1. Name of conveying party(ies):

Chao-Cheng Lee
An-Ming Lee

10-23-02

Additional names(s) of conveying party(ies) Yes No

2. Name and address of receiving party(ies):

Name: Realtek Semiconductor Corp.

Address: No. 2, Industry E. Road IX

Science-Based Industrial Park

City: Hsinchu State/Prov.: _____

Country: Taiwan, R.O.C. ZIP: _____

Additional name(s) & address(es) Yes No

jc931 U.S. PTO
10/278506
10/23/02

3. Nature of conveyance:

- Assignment Merger
- Security Agreement Change of Name
- Other _____

Execution Date: October 4, 2002

4. Application number(s) or patent numbers(s):

If this document is being filed together with a new application, the execution date of the application is: 10/4/02

10/278506

Patent Application No. Filing date

B. Patent No.(s)

Additional numbers Yes No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Raymond Sun

Registration No. 35,699

Address: 12420 Woodhall Way

City: Tustin State/Prov.: CA

Country: U.S.A. ZIP: 92782

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41):.....\$ 40.00

- Enclosed - Any excess or insufficiency should be credited or debited to deposit account
- Authorized to be charged to deposit account

8. Deposit account number:

(Attach duplicate copy of this page if paying by deposit account)

10/29/2002 BYRNE 00000130 10278506
01 FC:0021 40.00 DP

DO NOT USE THIS SPACE

9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Raymond Sun

Name of Person Signing

Signature

10-23-02

Date

3

Total number of pages including cover sheet, attachments, and

ASSIGNMENT

Attorney Docket No. Y050-176

- (1-8) Insert Name(s) of Inventor(s)
 - (1) Chao-Cheng Lee (5) _____
 - (2) An-Ming Lee (6) _____
 - (3) _____ (7) _____
 - (4) _____ (8) _____

In consideration of the sum of one dollar (\$1.00) and other good and valuable considerations paid to each of the undersigned, the undersigned agree(s) to assign, and hereby does assign, transfer and set over to

(1-9) Insert name of Assignee (9) Realtek Semiconductor Corp.

(10) Insert state of Incorporation of Assignee (10) Hsinchu, Taiwan

(11) Insert address of Assignee (11) of No.2, Industry E. Rd., IX, Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C. (hereinafter designated as the Assignee) the entire worldwide right, title and interest in the invention known as

(12) Insert identification of Invention, such as Title, Case Number or Foreign Application Number (12) **Impedance Matching Circuit With Automatic Adjustment and Method Thereof** (Case No. 910267.IE1) for which the undersigned has (have) executed an application for patent in the United States of America

(13) Insert Date of Signing of Application (13) on 10-4-02

1) The undersigned agree(s) to execute all papers necessary in connection with the application and any continuing or divisional applications thereof and also to execute separate assignments in connection with such applications as the Assignee may does necessary or expedient.

2) The undersigned agree(s) to execute all papers necessary in connection with any interference which may be declared concerning this application or continuation or division thereof and to cooperate with the Assignee in every way possible in obtaining evidence and going forward with such interference.

3) The undersigned agree(s) to execute all papers and documents and perform any act which may be necessary in connection with claims or provisions of the international Convention for Protection of Industrial Property or similar agreements.

4) The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States patent to the Assignee.

5) The undersigned hereby authorize(s) and request(s) the Commissioner of Patens to issue any and all Letters Patents of the United States resulting from said application or any division or divisions or continuing applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) full right to convey the entire interest herein assigned, and that he has (they have) not executed and will not execute, any agreement in conflict herewith.

6) The undersigned hereby grants RAYMOND SUN, Reg. No.35,699, the power to insert on this assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent & Trademark Office for recordation of this document.

Date: <u>10-2-02</u>	Name of Inventor: <u>李安明 An-Ming Lee</u>	(SEAL)
Date: <u>10-2-02</u>	Name of Inventor: <u>李朝成 Chao-Cheng Lee</u>	(SEAL)
Date: _____	Name of Inventor: _____	(SEAL)
Date: _____	Name of Inventor: _____	(SEAL)
Date: _____	Name of Inventor: _____	(SEAL)
Date: _____	Name of Inventor: _____	(SEAL)